



BSS84AKQB

50 V, P-channel Trench MOSFET

13 July 2021

Product data sheet

1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in an ultra small DFN1110D-3 (SOT8015) leadless Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Logic-level compatible
- Side wettable flanks for optical solder inspection
- Ultra small and leadless SMD plastic package: 1.1 x 1 x 0.48 mm
- Trench MOSFET technology
- ElectroStatic Discharge (ESD) protection > 1 kV HBM (Class H1C)
- AEC-Q101 qualified

3. Applications

- Relay driver
- High-speed line driver
- High-side load switch
- Switching circuits

4. Quick reference data

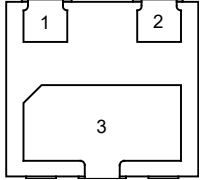
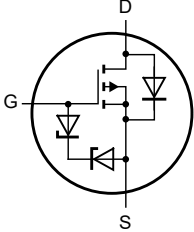
Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------------------------|----------------------------------|---|-----|-----|------|----------|
| V_{DS} | drain-source voltage | $T_j = 25\text{ °C}$ | - | - | -50 | V |
| V_{GS} | gate-source voltage | | -20 | - | 12 | V |
| I_D | drain current | $V_{GS} = -10\text{ V}; T_{amb} = 25\text{ °C}$ | [1] | - | -270 | mA |
| Static characteristics | | | | | | |
| R_{DSon} | drain-source on-state resistance | $V_{GS} = -10\text{ V}; I_D = -100\text{ mA}; T_j = 25\text{ °C}$ | - | 3.8 | 7.5 | Ω |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm².

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------|---|--|
| 1 | G | gate |  <p>DFN1110D-3 (SOT8015)</p> |  <p>017aaa259</p> |
| 2 | S | source | | |
| 3 | D | drain | | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|-------------|------------|--|---------|
| | Name | Description | Version |
| BSS84AKQB | DFN1110D-3 | plastic, leadless extremely thin small outline package with side-wettable flanks (SWF); 3 terminals; 0.65 mm pitch; 1.1 mm x 1 mm x 0.48 mm body | SOT8015 |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| BSS84AKQB | B9 |

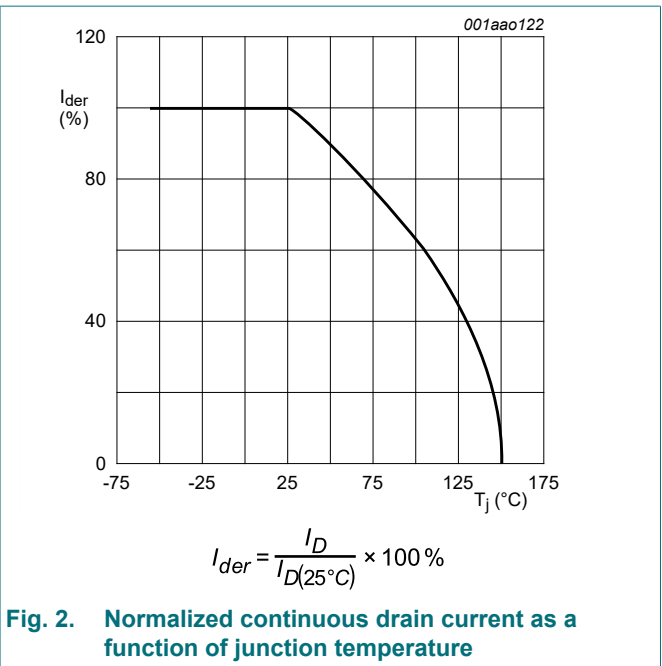
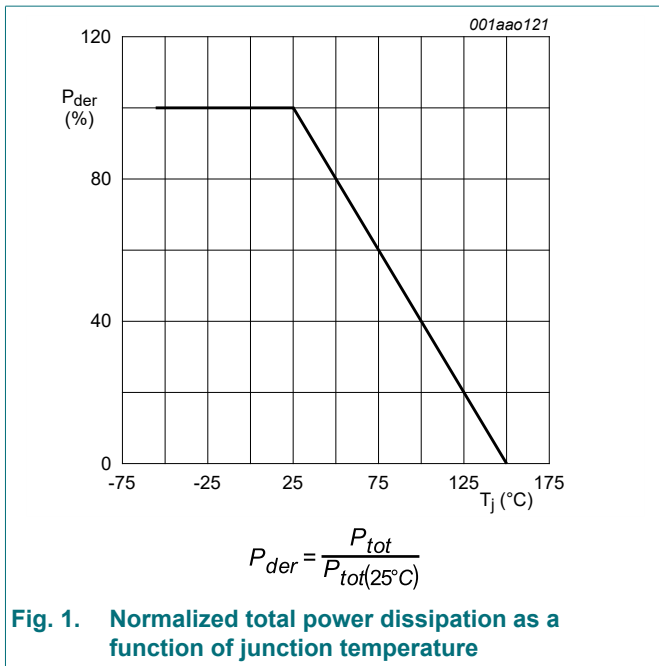
8. Limiting values

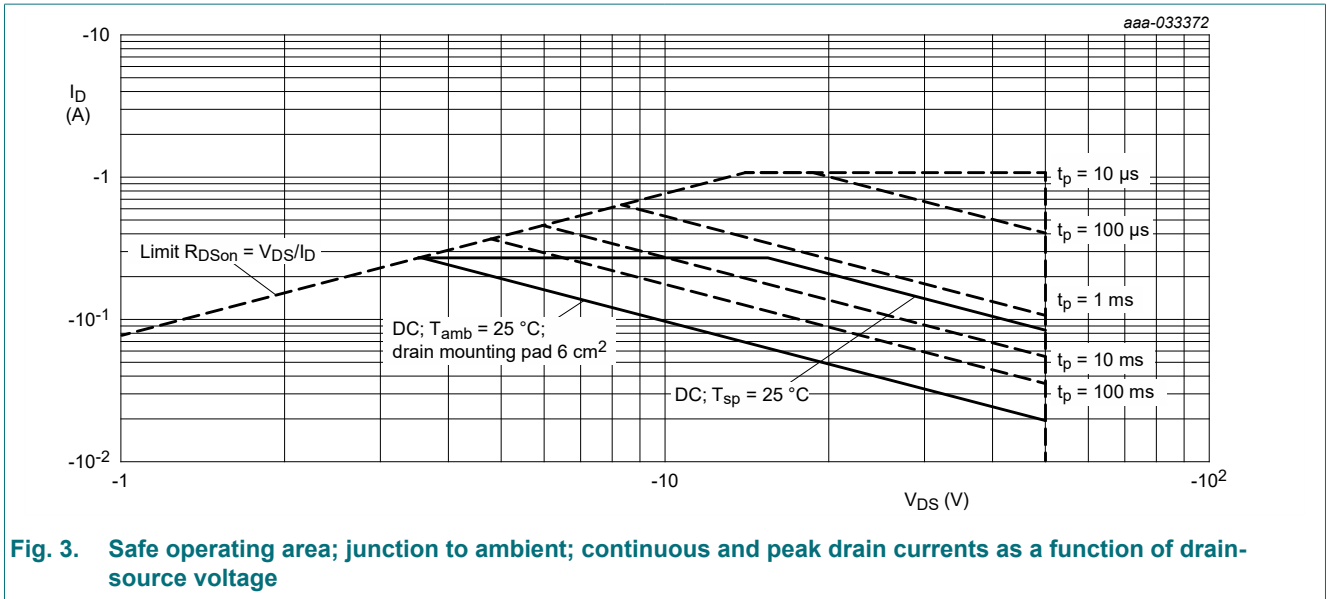
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|-----------------------------|--|--|-----|-----|------|------|
| V _{DS} | drain-source voltage | T _j = 25 °C | | - | -50 | V |
| V _{GS} | gate-source voltage | | | -20 | 12 | V |
| V _{GSMlim} | peak gate-source voltage | δ _{factor} = 0.1; t _p = 50 μs | | -20 | 20 | V |
| I _D | drain current | V _{GS} = -10 V; T _{amb} = 25 °C | [1] | - | -270 | mA |
| | | V _{GS} = -10 V; T _{amb} = 100 °C | [1] | - | -170 | mA |
| I _{DM} | peak drain current | T _{amb} = 25 °C; single pulse; t _p ≤ 10 μs | | - | -1.1 | A |
| P _{tot} | total power dissipation | T _{amb} = 25 °C | [2] | - | 420 | mW |
| | | | [1] | - | 960 | mW |
| | | T _{sp} = 25 °C | | - | 4.2 | W |
| T _j | junction temperature | | | -55 | 150 | °C |
| T _{amb} | ambient temperature | | | -55 | 150 | °C |
| T _{stg} | storage temperature | | | -65 | 150 | °C |
| Source-drain diode | | | | | | |
| I _S | source current | T _{amb} = 25 °C | [1] | - | -115 | mA |
| ESD maximum rating | | | | | | |
| V _{ESD} | electrostatic discharge voltage | HBM | | - | 1000 | V |
| Avalanche ruggedness | | | | | | |
| E _{DS(AL)S} | non-repetitive drain-source avalanche energy | T _{j(initial)} = 25 °C; I _D = 0.05 A; DUT in avalanche (unclamped) | | - | 1.2 | mJ |

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm².
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.





9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|----------------|--|-------------|-----|-----|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1] | - | 245 | 300 | K/W |
| | | | [2] | - | 110 | 130 | K/W |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | | | - | 25 | 30 | K/W |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 6 cm².

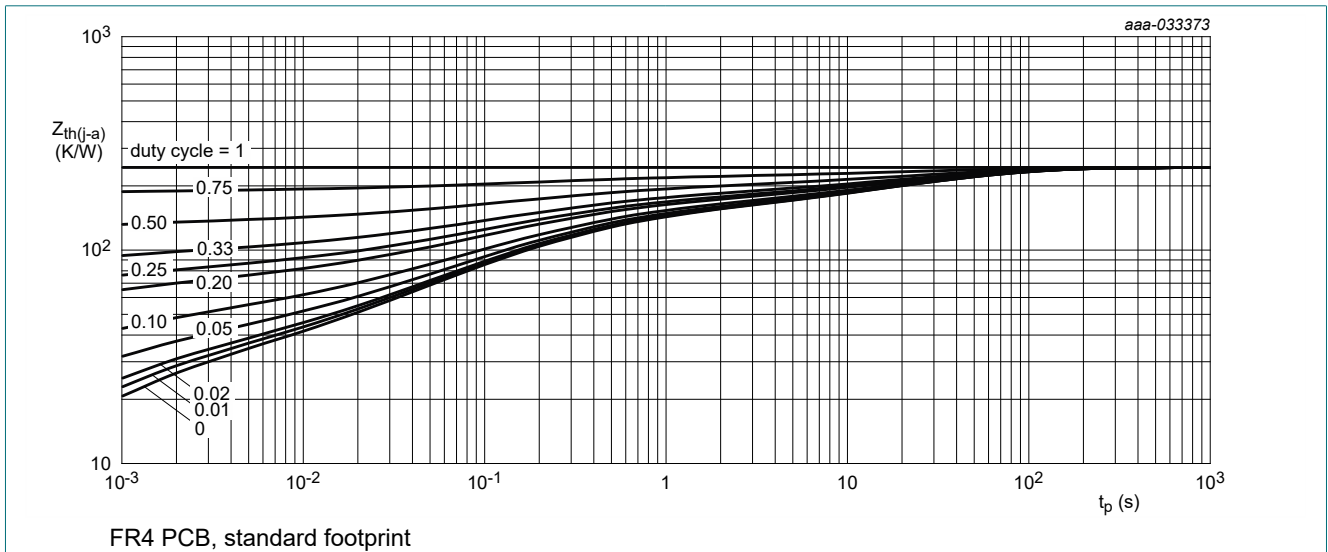


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

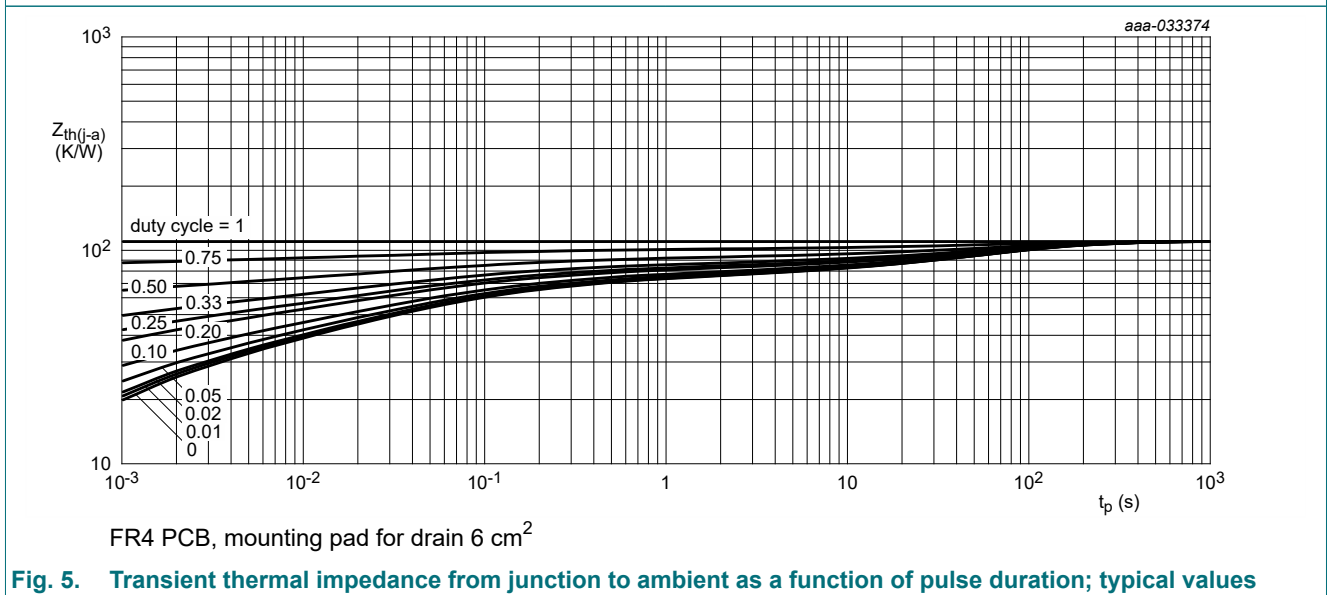


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------------------------------|----------------------------------|--|---|------|------|---------------|
| Static characteristics | | | | | | |
| $V_{(BR)DSS}$ | drain-source breakdown voltage | $I_D = -250 \mu\text{A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | -50 | - | - | V |
| V_{GSth} | gate-source threshold voltage | $I_D = -250 \mu\text{A}; V_{DS} = V_{GS}; T_j = 25 \text{ }^\circ\text{C}$ | -1.1 | -1.6 | -2.1 | V |
| I_{DSS} | drain leakage current | $V_{DS} = -50 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | - | -1 | μA |
| I_{GSS} | gate leakage current | $V_{GS} = -20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | - | -10 | μA |
| | | $V_{GS} = 20 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | - | 10 | μA |
| R_{DSon} | drain-source on-state resistance | $V_{GS} = -10 \text{ V}; I_D = -100 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$ | - | 3.8 | 7.5 | Ω |
| | | $V_{GS} = -10 \text{ V}; I_D = -100 \text{ mA}; T_j = 150 \text{ }^\circ\text{C}$ | - | 6.7 | 13 | Ω |
| | | $V_{GS} = -4.5 \text{ V}; I_D = -100 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$ | - | 5 | 8.5 | Ω |
| g_{fs} | forward transconductance | $V_{DS} = -5 \text{ V}; I_D = -100 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$ | - | 0.2 | - | S |
| Dynamic characteristics | | | | | | |
| $Q_{G(tot)}$ | total gate charge | $V_{DS} = -25 \text{ V}; I_D = -0.1 \text{ A}; V_{GS} = -10 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 0.4 | 0.6 | nC |
| Q_{GS} | gate-source charge | | - | 0.1 | - | nC |
| Q_{GD} | gate-drain charge | | - | 0.1 | - | nC |
| C_{iss} | input capacitance | $V_{DS} = -25 \text{ V}; f = 1 \text{ MHz}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 23.2 | - | pF |
| C_{oss} | output capacitance | | - | 3.5 | - | pF |
| C_{rss} | reverse transfer capacitance | | - | 1.1 | - | pF |
| $t_{d(on)}$ | turn-on delay time | | $V_{DS} = -25 \text{ V}; I_D = -0.1 \text{ A}; V_{GS} = -10 \text{ V}; R_{G(ext)} = 6 \text{ } \Omega; T_j = 25 \text{ }^\circ\text{C}$ | - | 6 | - |
| t_r | rise time | | - | 9 | - | ns |
| $t_{d(off)}$ | turn-off delay time | | - | 40 | - | ns |
| t_f | fall time | | - | 22 | - | ns |
| Source-drain diode | | | | | | |
| V_{SD} | source-drain voltage | $I_S = -0.115 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | -0.7 | -1.2 | V |
| t_{rr} | reverse recovery time | $I_S = -0.1 \text{ A}; dI_S/dt = 100 \text{ A}/\mu\text{s}; V_{GS} = -10 \text{ V}; V_{DS} = -25 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 43 | - | ns |
| Q_r | recovered charge | | - | 39 | - | nC |

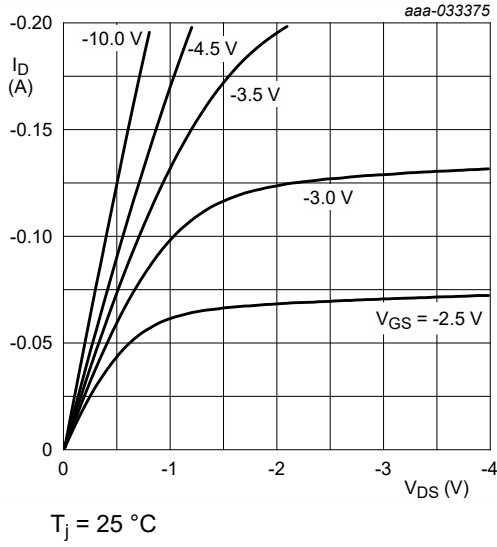


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

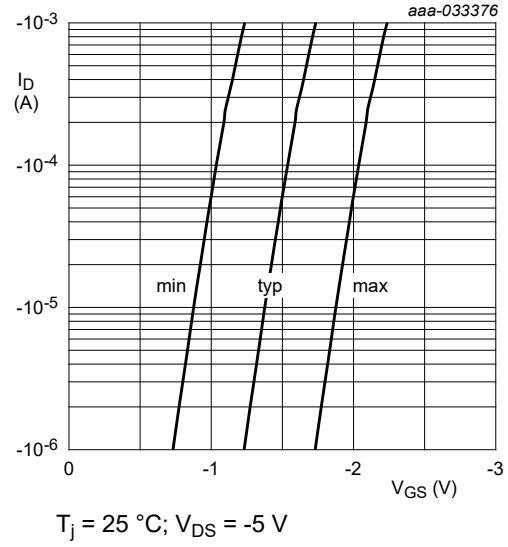


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

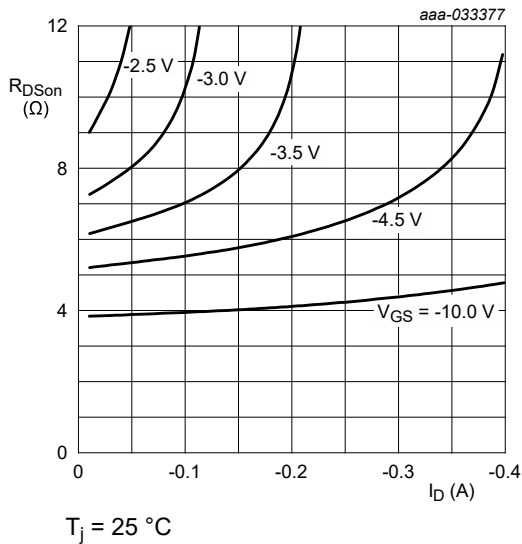


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

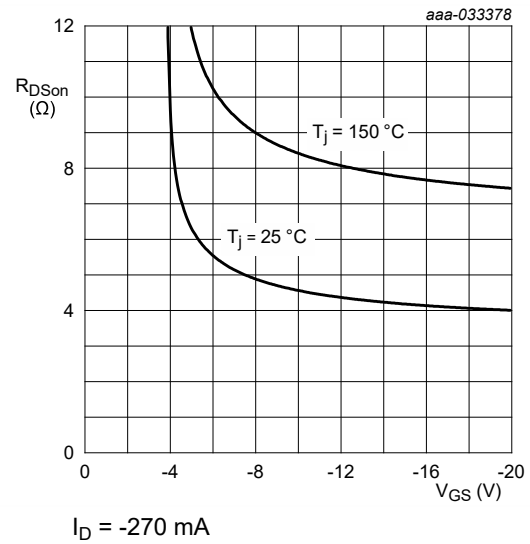


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

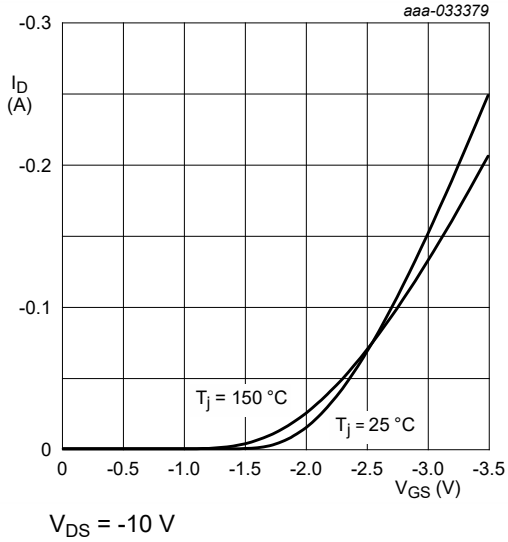
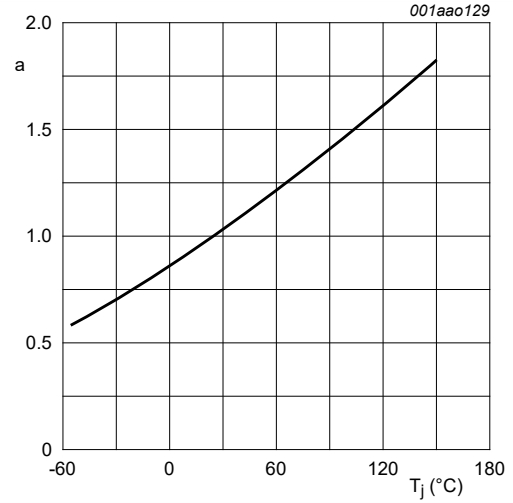


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values



$$a = \frac{R_{DSon}}{R_{DSon}(25^\circ\text{C})}$$

Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

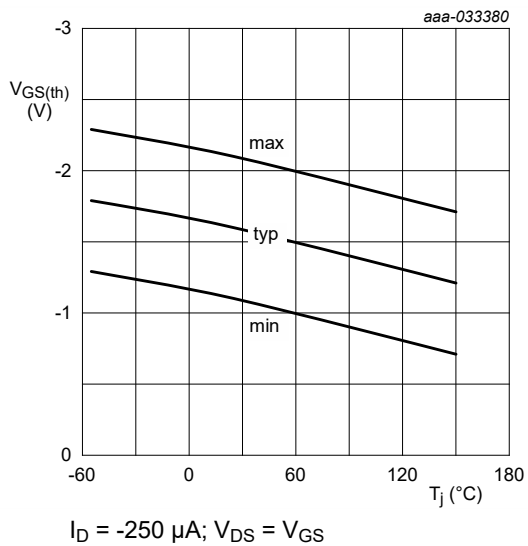


Fig. 12. Gate-source threshold voltage as a function of junction temperature

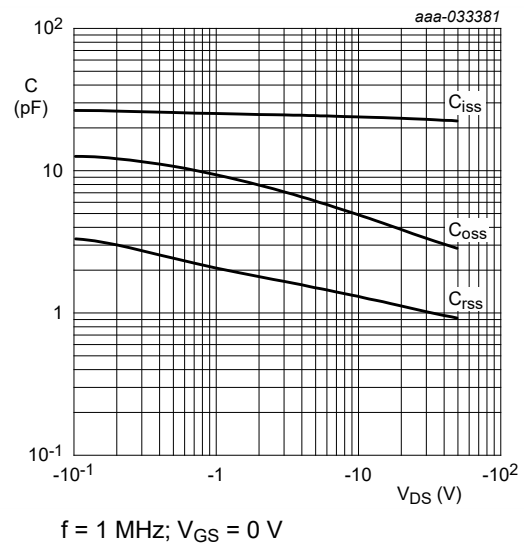
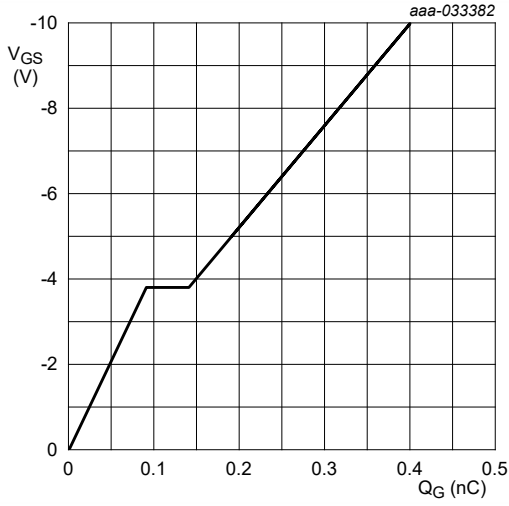


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$I_D = -0.1$ A; $V_{DS} = -25$ V; $T_j = 25$ °C

Fig. 14. Gate-source voltage as a function of gate charge; typical values

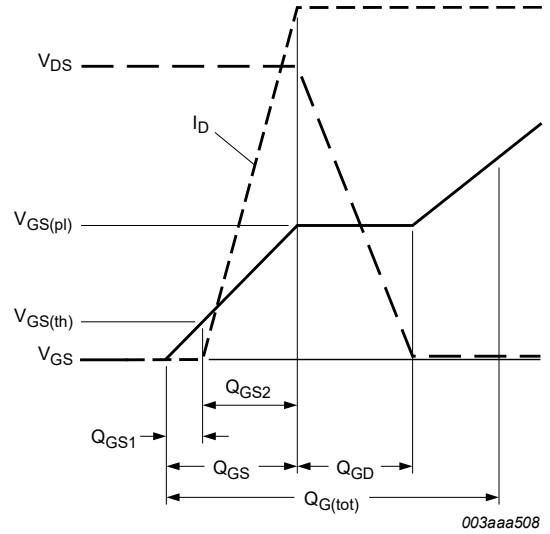
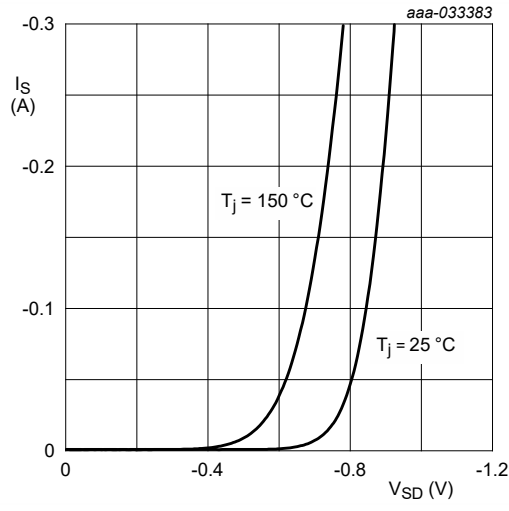


Fig. 15. Gate charge waveform definitions



$V_{GS} = 0$ V

Fig. 16. Source current as a function of source-drain voltage; typical values

11. Test information

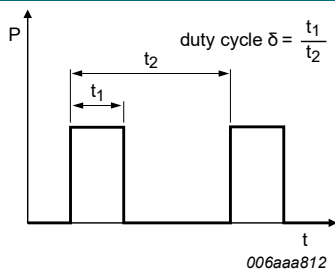


Fig. 17. Duty cycle definition

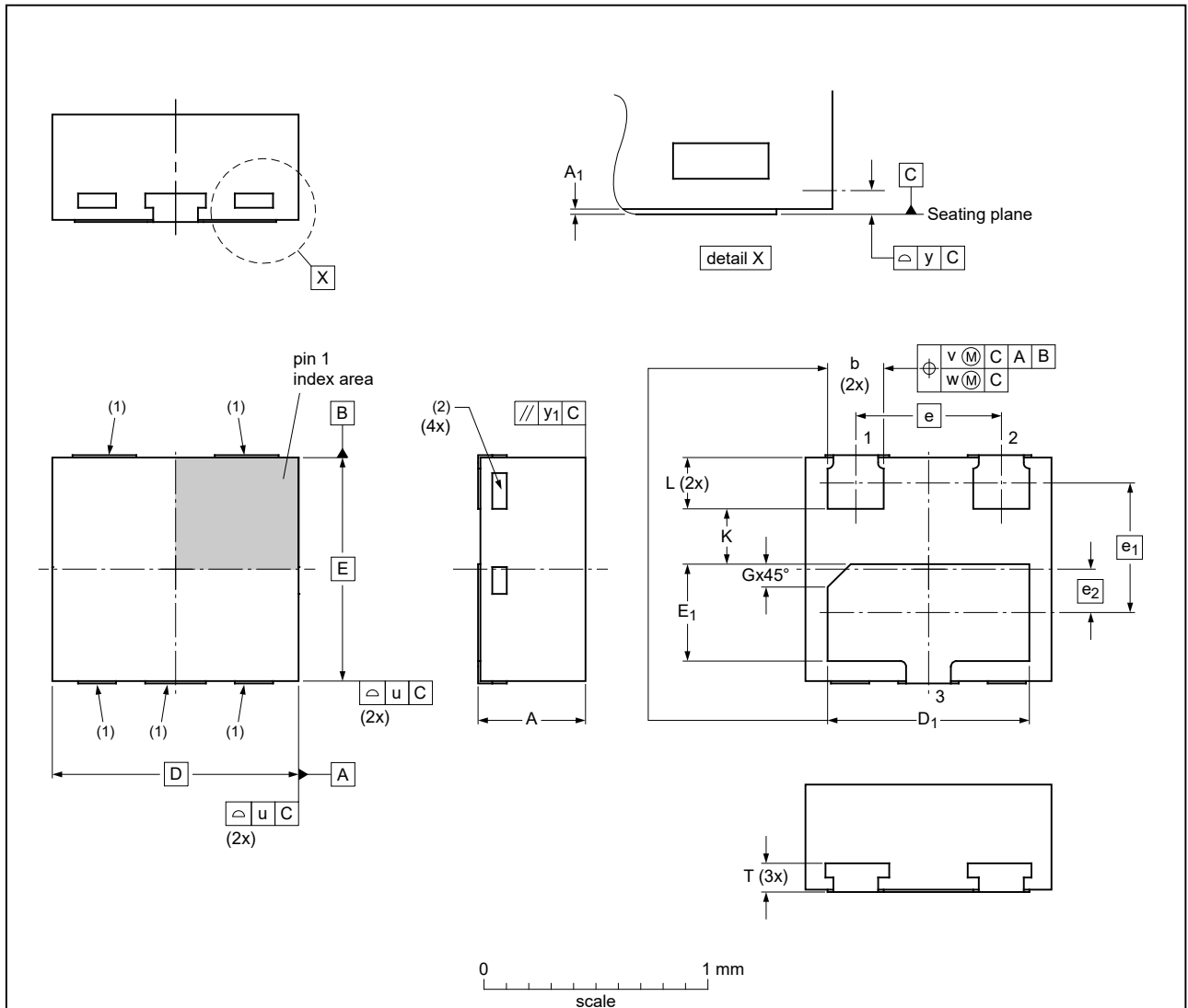
Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

DFN1110D-3: plastic, leadless extremely thin small outline package with side-wettable flanks (SWF); 3 terminals; 0.65 mm pitch; 1.1 mm x 1 mm x 0.48 mm body

SOT8015



Dimensions (mm are the original dimensions)

| Unit | A | A ₁ | b | D | D ₁ | E | E ₁ | e | e ₁ | e ₂ | G | K | L | T | u | v | w | y | y ₁ |
|------|------|----------------|------|-----|----------------|---|----------------|------|----------------|----------------|------------|-----|------|------|------|-----|------|------|----------------|
| max | 0.50 | 0.040 | 0.30 | | 0.95 | | 0.48 | | | | | | 0.27 | 0.22 | | | | | |
| nom | 0.47 | 0.020 | 0.25 | 1.1 | 0.90 | 1 | 0.43 | 0.65 | 0.58 | 0.19 | 0.09 (ref) | | 0.23 | 0.16 | 0.05 | 0.1 | 0.05 | 0.05 | 0.05 |
| min | 0.44 | 0.005 | 0.22 | | 0.87 | | 0.40 | | | | | 0.2 | 0.20 | 0.10 | | | | | |

Note

- Side Wettable Flank, protrusion max. 0.02 mm.
 - Visible depend upon used manufacturing technology.
- Dimension A and T are including plating thickness.

sot8015_po

| Outline version | References | | | | European projection | Issue date |
|-----------------|------------|----------|-------|--|---------------------|----------------------|
| | IEC | JEDEC | JEITA | | | |
| SOT8015 | | MO-340BA | | | | 19-12-02 19-12-04 |

Fig. 18. Package outline DFN1110D-3 (SOT8015)

13. Soldering

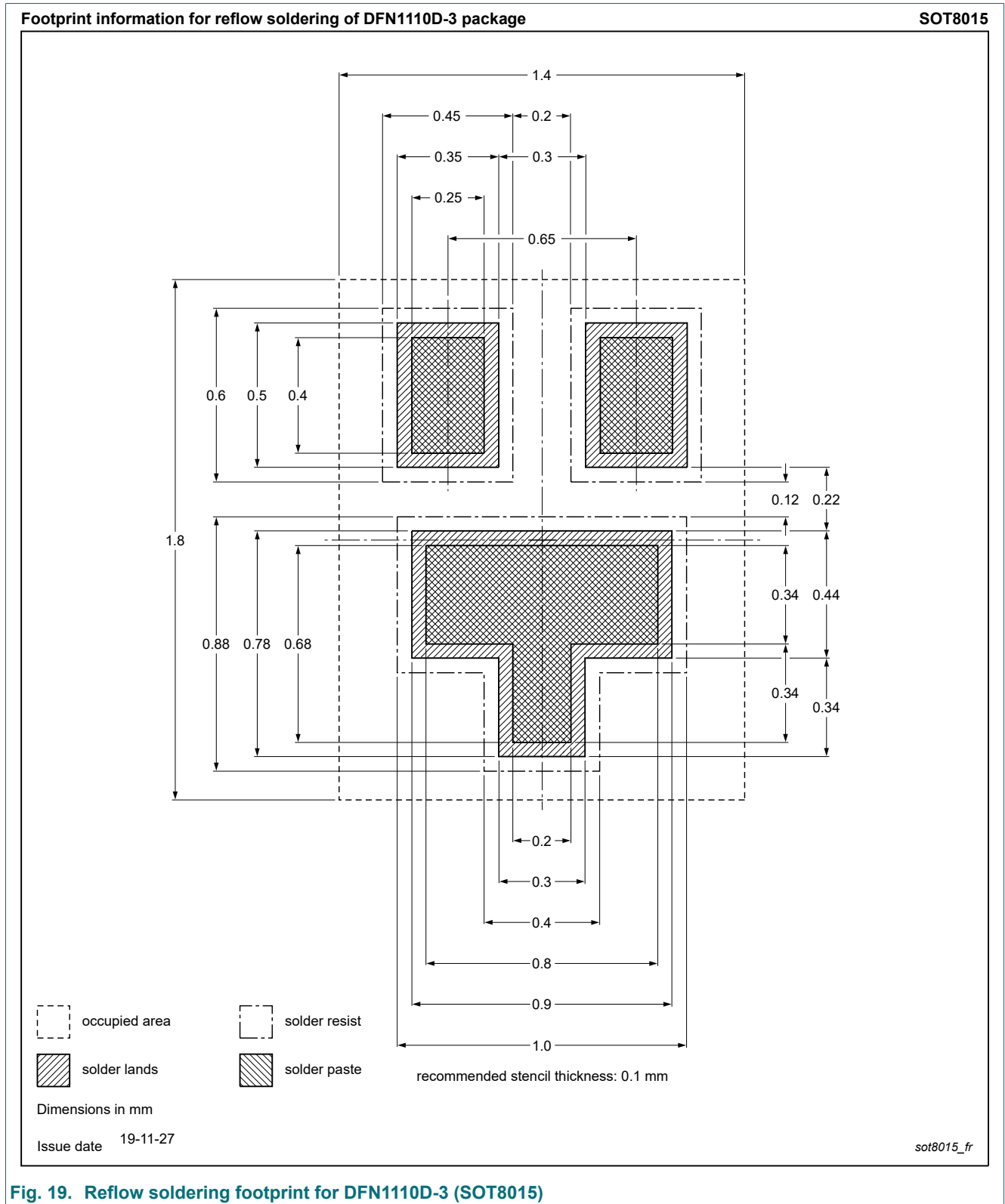


Fig. 19. Reflow soldering footprint for DFN1110D-3 (SOT8015)

14. Revision history

Table 8. Revision history

| Data sheet ID | Release date | Data sheet status | Change notice | Supersedes |
|---------------|--------------|--------------------|---------------|------------|
| BSS84AKQB v.1 | 20210713 | Product data sheet | - | - |

15. Legal information

Data sheet status

| Document status [1][2] | Product status [3] | Definition |
|--------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

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